

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-11 (cancelled).

12. (New) A carrier device for magnetizable substrates, comprising:
  - at least one magnetized base element, which has at least one receptacle for a substrate.
13. (New) The carrier device as recited in claim 12, wherein the substrate is a thin film substrate.
14. (New) The carrier device as recited in claim 12, wherein the base element includes a magnetized base metal sheet.
15. (New) The carrier device as recited in claim 14, wherein the receptacle for the substrate is one of a drilled hole, a stamped hole, or a passage with or without depressions in the base metal sheet, a shape and dimensions of the receptacle being tailored to the contour of the substrate.
16. (New) The carrier device as recited in claim 15, wherein the base metal sheet has multiple at least one of: i) drilled holes, ii) stamped holes, and iii) passages with or without depressions, which are positioned in a grid.
17. (New) The carrier device as recited in claim 12, wherein the substrate has a peripheral collar and a shape and dimensions of the receptacle being such that the collar of the substrate rests only partially on the base element.
18. (New) The carrier device as recited in claim 12, wherein the substrate has a collar, and a shape and dimension of the receptacle being such that the collar of the substrate rests only on an edge of the receptacle.

19. (New) The carrier device as recited in claim 12, wherein the base element is at least partially made of Sm<sub>4</sub>Co<sub>17</sub>.
20. (New) The corner device as recited in claim 12, wherein the base element is at least partially made of a ferromagnetic material.
21. (New) The carrier device as recited in claim 12, further comprising at least one cover element configured to be situated on the base element from at least one of above and below, relative to the base element, the at least one cover being used during a processing of substrate.
22. (New) The carrier device as recited in claim 21, wherein the at least one cover element is configured for a wet process, the at least one cover element having through openings or high media transparency.
23. (New) The carrier device as recited in claim 21, wherein the at least one cover element is configured for layer deposition.
24. (New) The carrier device as recited in claim 21, wherein the at least one cover element is configured for shadow mask deposition.
25. (New) The carrier device as recited in claim 21, wherein the at least one cover element is implemented in a form of sheets, each sheet being provided with at least one of: i) drilled holes, ii) stamped holes, and iii) passages with or without depressions.